



# Technical Data Sheet

## Topadd® TF-869

### Description

TF-869 is styrene-acrylonitrile copolymer with ultra-high molecular weight which amounts to 5 million. It functions as a processing aid for ABS, ASA, ABS/PC alloy and PVC with high heat resistance.

### Advantage

- Excellent fusion promotion, very fast fusion
- Good cost-performance
- Good surface-gloss of finished product
- No affection on Vicat softening points

### Tech Spec

Specification	Unit	Test standard	TF-869
Appearance	--	--	White powder
Bulk density	g/cm <sup>3</sup>	GB/T 1636-2008	0.45±0.10
Sieve residue (40 mesh)	%	GB/T 2916	≤2.0
Volatile content	%	ASTM D5668	≤1.5
Intrinsic viscosity (η)	--	GB/T 16321.1-2008	11-12
Molecular weight (million)	million	--	5.0

### Application

TF-869 can be used in ABS, ASA, PC, PBT, ABS/PC alloys. It also can be used as a foam regulator in PVC foam products.

### Similar products

Chemtura : Blendex B-869

### Package and Storage

25kg PP woven bag with PE liner or 20kg paper bag with PE liner

Should be stored in a dry and ventilated storeroom. This product is non-dangerous.

For other operations, please refer to SDS instructions provided by the manufacturer.

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